



Advanced Product / Process Change Notice

No.: Z200-APCN-OM201309-01-P

Date: September 23, 2013.

<p>Change Title : <u>1Gb (128Mb x8 and 64Mb x16) DDR2 technology migration from 65nm to 45nm</u></p> <p>Change Classification: <input checked="" type="checkbox"/> Major <input type="checkbox"/> Minor</p> <p>Change item : <input checked="" type="checkbox"/> Design <input type="checkbox"/> Raw Material <input checked="" type="checkbox"/> Wafer FAB <input type="checkbox"/> Package Assembly <input type="checkbox"/> Testing <input type="checkbox"/> Others :</p>					
<p>Affected Product(s) :</p> <p>W971GG6JB (64Mx16 DDR2 with 65nm technology)</p> <p>W971GG8JB (128Mx16 DDR2 with 65nm technology)</p>					
<p>Description of Change(s) :</p> <p>(1) Technology migration (65nm → 45nm) for 1Gb DDR2</p> <p>(2) New wafer manufacturing fab: Powerchip Semiconductor Corp. (Here-in-after: PSC, Address: No. 12, Li-Hsin Rd. 1, Hsinchu Science Park, Hsinchu, Taiwan)</p>					
<p>Reason for Change(s) :</p> <p>According to Winbond product roadmap, launch new 1G DDR2 with 45nm technology</p>					
<p>Impact of Change(s) : (positive & negative)</p> <p>Form : no change</p> <p>Fit : No change</p> <p>Function : No concern (fully compatible between 65nm and 45nm)</p> <p>Reliability : In progress</p> <p>Hazardous Substances: In progress</p>					
<p>Qualification Plan/ Results :</p> <p>(1) The qualification is in progress and expected come out in November/E/2013.</p> <p>(2) PSC is one company with TS16949 and OHSAS 18001 certificated company (Please refer to Attachment)</p>					
<p>Implementation Plan :</p> <p><input type="checkbox"/> Date Code : _____ onward <input type="checkbox"/> Lot No.: _____ onward <input checked="" type="checkbox"/> Proposed first ship date: <u>December/30/2013 (schedule).</u></p> <p>The follow-up disposition of 65nm 1Gb DDR2:</p> <p>1) The date of Last-buy orders for the 65nm 1Gb DDR2: March. 31, 2014.</p> <p>2) The last shipment date of the 65nm 1Gb DDR2: June.30, 2014.</p>					
Originator: (QA Sec. Manager)	<i>YH Cheng</i>	Approval: (QA Dept. Manager)	<i>YH Cheng</i>	Approval: (QRA Director)	<i>Yu-Sung, Cheng</i>
Contact for Questions & Concerns		<p>Name: <u>Hannah Cheng</u> TEL:<u>886-3-5678168</u> (ext.6553) FAX: <u>886-3-5796124</u></p> <p>Address : <u># 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan</u></p> <p>E-mail: <u>yhcheng2@winbond.com</u></p>			



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Approval Disapproval Conditional Approval : _____.

Comment:

Date: _____

Dept. name: _____

Person in charge: _____



Table 1 The part no comparison table

Product	65nm Part No	45nm Part No
64Mx16 DDR2	W971GG6JB	W971GG6KB
128Mx8 DDR2	W971GG8JB	W971GG8KB